



Material Content Data Sheet



Sales Product Name		SAK-XC822MT-1FRA AA		Issued		29. August 2013		
MA#		MA000874756						
Package		PG-TSSOP-16-1		Weight*		59.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.168	5.29	5.29	52858	52858
leadframe	non noble metal	nickel	7440-02-0	8.109	13.53		135307	
	non noble metal	iron	7439-89-6	11.199	18.69	32.22	186852	322159
wire	noble metal	gold	7440-57-5	0.300	0.50	0.50	5013	5013
encapsulation	organic material	carbon black	1333-86-4	0.104	0.17		1728	
	plastics	epoxy resin	-	4.385	7.32		73163	
	inorganic material	silicondioxide	60676-86-0	30.038	50.10	57.59	501194	576085
leadfinish	non noble metal	tin	7440-31-5	0.915	1.53	1.53	15264	15264
plating	noble metal	silver	7440-22-4	0.856	1.43	1.43	14289	14289
glue	plastics	acrylic resin	-	0.189	0.32		3153	
	noble metal	silver	7440-22-4	0.670	1.12	1.44	11179	14332
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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